The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A product management system comprising:

a first resonance circuit;

a second resonance circuit; and

a reader/writer for at least one of reading information stored in a semiconductor device and writing information in the semiconductor device,

wherein the first resonance circuit comprises [[an]] a first antenna coil and a first capacitor,

wherein the second resonance circuit comprises a second antenna coil and a second capacitor,

wherein a first packing material for packing a product is provided with the first resonance circuit,

wherein a second packing material for packing the first packing material is provided with the second resonance circuit,

wherein the product is provided with the semiconductor device,

wherein the second resonance circuit can communicate with the reader/writer and the first resonance circuit, and

wherein the first resonance circuit can communicate with the ~~reader/writer~~ second resonance circuit and the semiconductor device.

2. (Currently Amended) The product management system according to Claim 1, wherein a communication method between the reader/writer and the first resonance ~~circuit is identical to~~ circuit, a communication method between the first resonance circuit and the ~~semiconductor device~~ second resonance circuit, and a communication method

between the second resonance circuit and the semiconductor device are identical to each other.

3. (Original) The product management system according to Claim 2, wherein the communication method is an electromagnetic induction method.

4. (Currently Amended) The product management system according to Claim 1, wherein a communication method between the reader/writer and the second resonance circuit is different from a communication method between the first resonance circuit and the semiconductor device.

5. (Currently Amended) The product management system according to Claim 4, wherein the communication method between the reader/writer and the second resonance circuit is any one of an electromagnetic induction method and a microwave method.

6. (Currently Amended) A product management system comprising:

a first resonance circuit;

a second resonance circuit; and

a reader/writer for at least one of reading information stored in a semiconductor device and writing information in the semiconductor device,

wherein the first resonance circuit comprises [[an]] a first antenna coil and a first capacitor,

wherein the second resonance circuit comprises a second antenna coil and a second capacitor,

wherein a first packing material for packing a product is provided with the first resonance circuit,

wherein a second packing material for packing the first packing material is provided with the second resonance circuit,

wherein the product is provided with the semiconductor device,

wherein the second resonance circuit can communicate with the reader/writer and the first resonance circuit,

wherein the first resonance circuit can communicate with the ~~reader/writer~~ second resonance circuit and the semiconductor device; and

wherein a communication range between the reader/writer and the resonance circuit is longer than a communication range between the resonance circuit and the semiconductor device.

7. (Currently Amended) The product management system according to Claim 6, wherein a communication method between the reader/writer and the second resonance circuit is any one of an electromagnetic induction method and a microwave method.

8. (Currently Amended) The product management system according to ~~any one of Claims~~ Claim 1 [[and]] or 6, wherein the semiconductor device is selected from the group of an ID tag, an ID chip, an ID label, an ID seal and an ID sticker.

9. (Currently Amended) A method comprising:

sending at least one of a first signal comprising first information and a first electric power from a reader/writer to a resonance circuit, wherein the resonance circuit comprises thin film integrated circuit portions comprising an antenna coil and a capacitor;

sending at least one of a second signal comprising the first information and a second electric power from the resonance circuit to a semiconductor device in response to a receipt of said at least one of the first signal and the first electric power, wherein

said semiconductor device comprises a thin film integrated circuit comprising a thin film transistor, and an antenna;

sending a third signal comprising second information from said semiconductor device to the resonance circuit in response to a receipt of said at least one of the second signal and the second electric power by the semiconductor device

sending a fourth signal comprising said second information from the resonance circuit to the reader/writer,

wherein the semiconductor device is attached to a product, the product is contained in a packing material, the resonance circuit is attached to the packing material and the reader/writer is disposed outside of the packing material.

10. (Previously Presented) A method comprising:

sending at least one of a first signal comprising first information and a first electric power from a reader/writer to a first resonance circuit,

sending at least one of a second signal comprising the first information and a second electric power from the first resonance circuit to a second resonance circuit in response to a receipt of said at least one of the first signal and the first electric power,

sending at least one of a third signal comprising the first information and a third electric power from the second resonance circuit to a semiconductor device in response to a receipt of said at least one of the second signal and the second electric power, wherein said semiconductor device comprises a thin film integrated circuit comprising a thin film transistor, and an antenna;

sending a fourth signal comprising second information from said semiconductor device to the second resonance circuit in response to a receipt of said at least one of the third signal and the third electric power by the semiconductor device,

sending a fifth signal comprising said second information from the second resonance circuit to the first resonance circuit,

sending a sixth signal comprising said second information from the first resonance circuit to the reader/writer,

wherein the semiconductor device is attached to a product, the product is contained in a second packing material, the second resonance circuit is attached to the second packing material, the second packing material is contained in a first packing material, the first resonance circuit is attached to the first packing material, and the reader/writer is disposed outside of the first packing material.

11. (Currently Amended) The method according to ~~any one of Claims~~ Claim 9 [[and]] or 10, wherein the semiconductor device is selected from the group of an ID tag, an ID chip, an ID label, an ID seal and an ID sticker.

12. (Previously Presented) The method according to Claim 10, wherein the first packing material is selected from the group of a suitcase, a corrugated fiberboard, a container and a transporting vehicle.

13. (Currently Amended) A product management system comprising:

a semiconductor device;

a resonance circuit; and

a reader/writer for at least one of reading information stored in the semiconductor device and writing information in the semiconductor device

wherein the resonance circuit comprises thin film integrated circuit portions, an antenna coil and a capacitor,

wherein a packing material for packing a product is provided with the resonance circuit,

wherein the product is provided with the semiconductor device,

wherein the semiconductor device comprises a thin film integrated circuit comprising a thin film transistor, and an antenna, and

wherein the resonance circuit can communicate with the reader/writer and the semiconductor device.

14. (Previously Presented) The product management system according to Claim 13, wherein a communication method between the reader/writer and the resonance circuit is identical to a communication method between the resonance circuit and the semiconductor device.

15. (Previously Presented) The product management system according to Claim 14, wherein the communication method is an electromagnetic induction method.

16. (Previously Presented) The product management system according to Claim 13, wherein a communication method between the reader/writer and the resonance circuit is different from a communication method between the resonance circuit and the semiconductor device.

17. (Previously Presented) The product management system according to Claim 16, wherein the communication method between the reader/writer and the resonance circuit is any one of an electromagnetic induction method and a microwave method.

18. (New) The method according to claim 9, wherein the resonance circuit further comprises any one of a battery, a CPU and a memory.

19. (New) The method according to claim 13, wherein the resonance circuit further comprises any one of a battery, a CPU and a memory.